semiconductor packaging news

EV Group and Dymek Form JV Company in Malaysia to Enhance Regional Support – May 26, 2023

semiconductor packaging news

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May 26, 2023

Chiplet Planning Kicks Into High Gear

Chiplets are beginning to impact chip design, even though they are not yet mainstream and no commercial marketplace exists for this kind of hardened IP. There are ongoing discussions about silicon lifecycle management, the best way to characterize and connect these devices, and how to deal with such issues as uneven aging and thermal mismatch. In addition, a big effort is underway to improve ...

Semiconductor Engineering

View Recorded Webinar Novel "Clean Peel-Release"

high shear bonding wafer processing adhesive to 350°C. WEBINAR: "Multiplying Wafer Processing Throughput with Novel Wafer Processing Adhesives" View now. A.I. Technology, Inc.





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Global Semiconductor Packaging Materials Market to Near \$30 Billion by 2027

Powered by strong demand for new electronics innovations, the global semiconductor packaging materials market is expected to reach US\$29.8 billion by 2027, a compound ...

SEMI

Packaging Solutions for Unique Markets

The MLF/QFN packaging technology is the fastest-growing IC packaging solution today. From a market segment perspective, MLF/QFN packaging solutions represent a >111B-unit ...

Technical Paper

Semiconductor: Chip nationalism is a 'blessing,' SEMI CEO says

The semiconductor industry represents the world's most essential and coveted technology. Semiconductors comprise the "brains" for everything, from mobile phones. ... **Techwire Asia**

Technical Papers

- Improving SiC Power Devices with Laser Ohmic Contact Formation
- Defluxing of Copper Pillar Bumped Flip-Chips
- Functional testing of 0.3mm pitch WLP
- Vacuum Fluxless Reflow Technology for Fine Pitch Interconnect Bumping Applications
- Master Advanced Packaging Inspection
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Do thin wafers have you frazzled? Our new ADJUST-A-VAC allows you to reduce the vacuum pressure from just below atmospheric pressure to up to ten inches of mercury. A LED bar display shows the vacuum level. Virtual Industries, Inc.





SEMI IS MORE ... Market Data

Xiaomi reaffirms commitment to proprietary chipsets after rival Oppo's recent closure of Zeku

Xiaomi has reaffirmed a commitment to developing its own chipsets after the abrupt closure of competitor Oppo's chip design unit Zeku, as the Beijing-based smartphone ...

South China Morning Post

China's Apple loss is India's gain, as 2022 supplier list shows shift in supply chain preferences

Apple added five new mainland Chinese suppliers while removing eight in mainland China in its latest financial year ended September 2022, after China's strict Covid-19 ...

South China Morning Post

The A.I. chip boom is pushing Nvidia toward \$1 trillion, but it won't help Intel and AMD

Nvidia's stock surged close to a \$1 trillion market cap in extended trading after it reported a shockingly strong forward outlook, and CEO Jensen Huang said the company ... CNBC



China's memory industry resisting impact of US trade sanctions

The US government's expanded restrictions on the Chinese semiconductor industry have posed a significant challenge to the development of the local memory industry. ...

Digitimes

A Highly Wasteful Industry

The systems industry as a whole is not concerned about power. I know that is a bold statement, but I believe it to be true. The semiconductor industry is mildly concerned, ...

Semiconductor Engineering

Taiwan fab toolmakers secure LTAs from China

Taiwan-based semiconductor equipment suppliers including Gudeng Precision Industrial, E&R Engineering, Marketech International, Nova Technology (Novatech) and ...

Digitimes

Thermally Conductive Silicone Compound Master Bond MasterSil 323AO-LO is a low outgassing silicone elastomer with a self-priming feature. It is electrically insulative and thermally conductive. Master Bond



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Automotive Relationships Shifting With Chiplets

The automotive industry is in the midst of a tremendous and rapid change on many fronts. OEMs are exploring new functions and features to add to their vehicles. ..

Semiconductor Engineering





Calendar

- May 30, 2023: 2023 IEEE 73rd Electronic Components and Technology Conference
- Jun 1, 2023: Overview of semiconductor manufacturing webinar for European attendees Jun 5, 2023: Overview of semiconductor manufacturing Webinar for Asian Attendees
- .
- Jun 8, 2023: Overview of semiconductor manufacturing / Austin, TX

Thermally Conductive

Silicone Compound Master Bond MasterSil 323AO-LO is a low outgassing silicone elastomer with a self-priming feature. It is electrically insulative and thermally conductive. Master Bond

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Test Your Knowledge

If an object is hastate what shape is it? See answer below.

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Press Releases

EV Group and Dymek Form JV Company in Malaysia to Enhance Regional Support

EV Group (EVG) announced that they have established a new joint venture company in Malaysia. The new company, called EV Group Malaysia Dymek Sdn. Bhd., will be charged ... EV Group

Imec and Brewer Science present process solutions for CVD oxide deposition processes at ECTC

Brewer Science, Inc. is presenting and exhibiting at Electronic Components and Technology Conference (ECTC) May 30th through June 2nd. Dr. Koen Kennes from imec is ... Brewer Science, Inc.

SEMI North America Advisory Board

Welcomes New Members

SEMI announced the election of two new members to the SEMI North America Advisory Board (NAAB): Maheen Hamid, co-founder, CFO and COO of Breker Verification Systems ... SEMI

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Increase throughput with the NanoResolution MRS Sensor that is 2-3X faster, delivering greater than 25 wafers (300mm) per hour. Learn more.



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Quote of the Day

"We make a living by what we get, we make a life by what we give."

Sir Winston Churchill

Keys to Reliable Tin Mitigation

A more reliable method to mitigate tin whiskers is the robotic hot solder dip processing of components



before assembly. This white paper identifies the key process considerations. Read more. **Circuit Technology Center**

Efficient Manufacture of IR Sensors

The market for IR sensing devices has been growing steadily but the challenge is how to manufacture them efficiently to achieve ROI. Read more.



Palomar Technologies, Inc.

What Year Was It?

First Published Dow Jones Industrial Averages

The Dow Jones Industrial Average was founded by Charles Dow and represented the dollar average of 12 stocks from leading American industries.

DOWIONES

The day was May 26. What year was it?

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Temporary Bonder & Debonder Wafer support system (i) 1- 20 conventional process and (ii) hybrid dual bonding process executed in vacuum and applicable to, 3D IC, FOWLP, and power devices. **Scientech Corporation**

Cartoon of the Day



"I am NOT sexist! I hired cheerleaders because they cost less than a motivational speaker." Copyright @ Randy Glasbergen

Better Bonds, with Atmospheric Plasma Our Atmospheric Plasma systems prepare surfaces for direct bonding, remove residue, and prepare surfaces for adhesion. Click Here to learn more. **Ontos Equipment Systems**



Test Your Knowledge Answer

If an object is hastate what shape is it? Answer: Triangular or shaped like an arrow, with two spreading lobes at the base.

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